2SD2693, 2SD2693A

Silicon NPN triple diffusion planar type

For power amplification Complementary to 2SB1724, 2SB1724A

■ Features

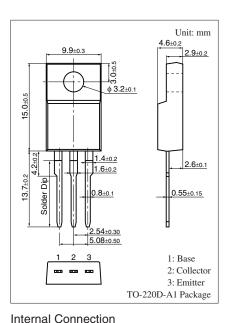
- Wide safe oeration area
- Satisfactory linearity of forward current transfer ratio h_{FE}
- Low collector-emitter saturation voltage V_{CE(sat)}
- Full-pack package which can be installed to the heat sink with one screw.

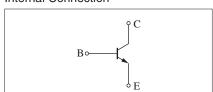
■ Absolute Maximum Ratings $T_C = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage	2SD2693	V _{CBO}	60	V
(Emitter open)	2SD2693A		80	
Collector-emitter voltage	2SD2693	V _{CEO}	60	V
(Base open)	2SD2693A		80	
Emitter-base voltage (Col	V _{EBO}	6	V	
Collector current	I_{C}	3	A	
Peak collector current *	I_{CP}	5	A	
Collector power dissipation	P _C	25	W	
	$T_a = 25^{\circ}C$		2.0	
Junction temperature	T _j	150	°C	
Storage temperature	T_{stg}	-55 to +150	°C	

Note) *: Non-repetitive peak collector current

■ Electrical Characteristics $T_C = 25$ °C ± 3 °C





Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage	2SD2693	V _{CEO}	$I_C = 30 \text{ mA}, I_B = 0$	60			V
(Base open) *1	2SD2693A			80			
Collector-base cutoff current (Emitter open)	2SD2693A	I_{CBO}	$V_{CB} = 80 \text{ V}, I_{E} = 0$			100	mA
Collector-emitter cutoff	2SD2693	I_{CEO}	$V_{CE} = 60 \text{ V}, I_{B} = 0$			100	μΑ
current (Base open)	2SD2693A		$V_{CE} = 80 \text{ V}, I_{B} = 0$				
Collector-emitter cutoff current (E-B short)	2SD2693	I _{CES}	$V_{CE} = 60 \text{ V}, I_{B} = 0$			100	μА
Emitter-base cutoff current (Col	lector open)	I_{EBO}	$V_{EB} = 6 \text{ V}, I_{C} = 0$			1	mA
Forward current transfer ratio *1		h _{FE1} *2	$V_{CE} = 4 \text{ V}, I_{C} = 1 \text{ A}$	70		250	_
		h _{FE2}	$V_{CE} = 4 \text{ V}, I_{C} = 3 \text{ A}$	10			
Collector-emitter saturation	voltage *1	V _{CE(sat)}	$I_C = 3 \text{ A}, I_B = 0.375 \text{ A}$			0.8	V
Transition frequency		f_T	$V_{CE} = 10 \text{ V}, I_{C} = 0.5 \text{ A}, f = 10 \text{ MHz}$		30		MHz
Turn-on time		t _{on}	I _C = 1 A, Resistance loaded		0.1		μs
Storage time		t _{stg}	$I_{B1} = 0.1 \text{ A}, I_{B2} = -0.1 \text{ A}$		2.3		μs
Fall time		$t_{\rm f}$	$V_{CC} = 50 \text{ V}$		0.3		μs

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

- 2. *1: Pulse measurement
 - *2: Rank classification

Rank	Q	Р		
$h_{\rm FE1}$	70 to 150	120 to 250		

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